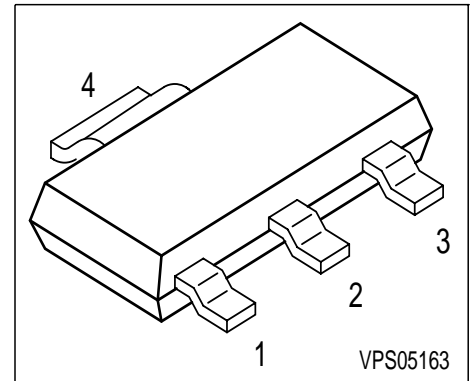


**NPN Silicon AF Power Transistor**

- For AF driver and output stages
- High collector current
- High current gain
- Low collector-emitter saturation voltage
- Complementary types: BDP952 ... BDP956 (PNP)



Type	Marking	Pin Configuration				Package
BDP951	BDP 951	1 = B	2 = C	3 = E	4 = C	SOT223
BDP953	BDP 953	1 = B	2 = C	3 = E	4 = C	SOT223
BDP955	PDP 955	1 = B	2 = C	3 = E	4 = C	SOT223

**Maximum Ratings**

Parameter	Symbol	BDP 951	BDP 953	BDP 955	Unit
Collector-emitter voltage	$V_{CEO}$	80	100	120	V
Collector-base voltage	$V_{CBO}$	100	120	140	
Emitter-base voltage	$V_{EBO}$	5	5	5	
DC collector current	$I_C$	3			A
Peak collector current	$I_{CM}$	5			
Base current	$I_B$	200			mA
Peak base current	$I_{BM}$	500			
Total power dissipation, $T_S = 99\text{ °C}$	$P_{tot}$	3			W
Junction temperature	$T_j$	150			°C
Storage temperature	$T_{sta}$	-65 ... 150			

**Thermal Resistance**

Junction - soldering point <sup>1)</sup>	$R_{thJS}$	≤17	K/W
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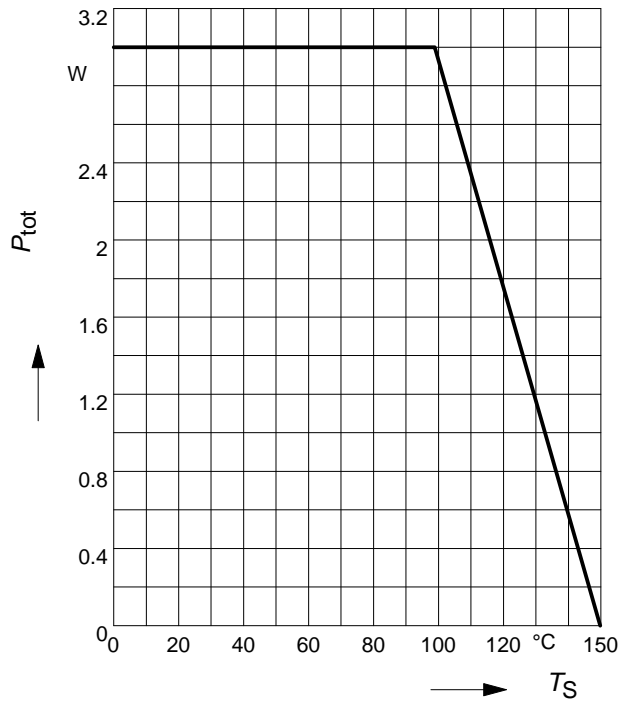
<sup>1)</sup>For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified.

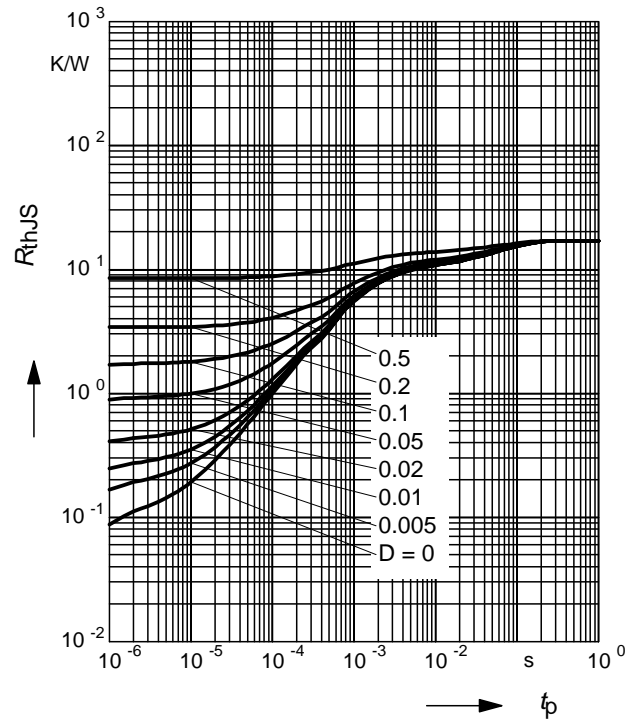
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage $I_C = 10\text{ mA}$ , $I_B = 0$	$V_{(BR)CEO}$	80	-	-	V
BDP951		100	-	-	
BDP953		120	-	-	
BDP955					
Collector-base breakdown voltage $I_C = 100\text{ }\mu\text{A}$ , $I_B = 0$	$V_{(BR)CBO}$	100	-	-	
BDP951		120	-	-	
BDP953		140	-	-	
BDP955					
Emitter-base breakdown voltage $I_E = 10\text{ }\mu\text{A}$ , $I_C = 0$	$V_{(BR)EBO}$	5	-	-	
Collector cutoff current $V_{CB} = 100\text{ V}$ , $I_E = 0$	$I_{CBO}$	-	-	100	nA
Collector cutoff current $V_{CB} = 100\text{ V}$ , $I_E = 0$ , $T_A = 150\text{ }^\circ\text{C}$	$I_{CBO}$	-	-	20	$\mu\text{A}$
Emitter cutoff current $V_{EB} = 4\text{ V}$ , $I_C = 0$	$I_{EBO}$	-	-	100	nA
DC current gain 1) $I_C = 10\text{ mA}$ , $V_{CE} = 5\text{ V}$ $I_C = 500\text{ mA}$ , $V_{CE} = 1\text{ V}$ $I_C = 2\text{ A}$ , $V_{CE} = 2\text{ V}$	$h_{FE}$	25 40 15	- - -	- 475 -	-
Collector-emitter saturation voltage1) $I_C = 2\text{ A}$ , $I_B = 0.2\text{ A}$	$V_{CEsat}$	-	-	0.8	V
Base-emitter saturation voltage 1) $I_C = 2\text{ A}$ , $I_B = 0.2\text{ A}$	$V_{BEsat}$	-	-	1.5	
AC Characteristics					
Transition frequency $I_C = 50\text{ mA}$ , $V_{CE} = 10\text{ V}$ , $f = 100\text{ MHz}$	$f_T$	-	100	-	MHz
Collector-base capacitance $V_{CB} = 10\text{ V}$ , $f = 1\text{ MHz}$	$C_{cb}$	-	25	-	pF

1) Pulse test:  $t \leq 300\text{ }\mu\text{s}$ ,  $D = 2\%$

**Total power dissipation  $P_{\text{tot}} = f(T_S)$**

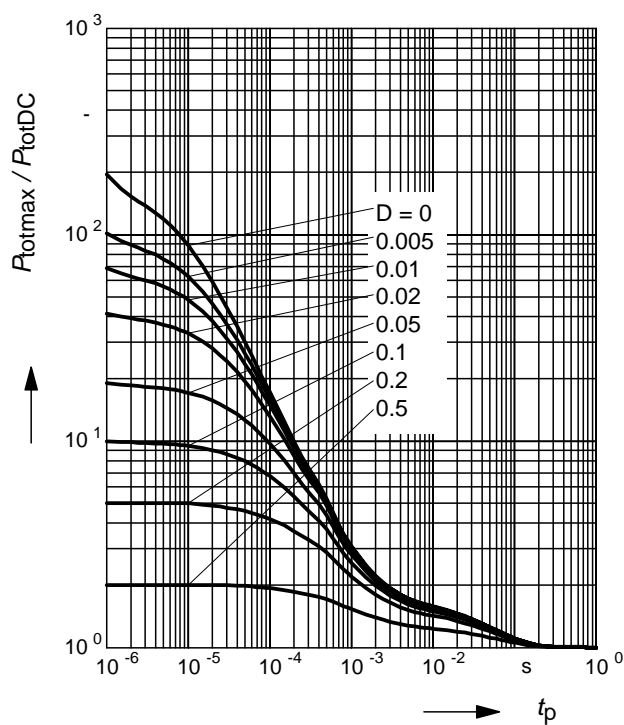


**Permissible Pulse Load  $R_{\text{thJS}} = f(t_p)$**



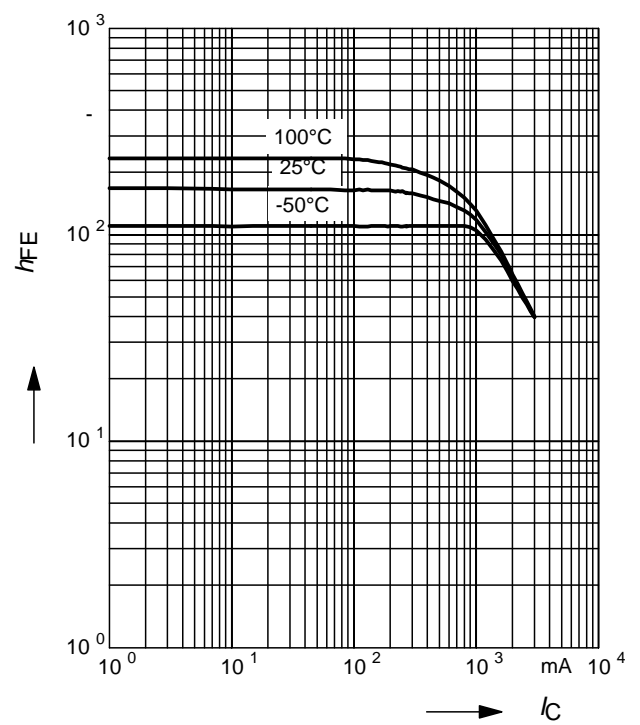
**Permissible Pulse Load**

$$P_{\text{totmax}} / P_{\text{totDC}} = f(t_p)$$



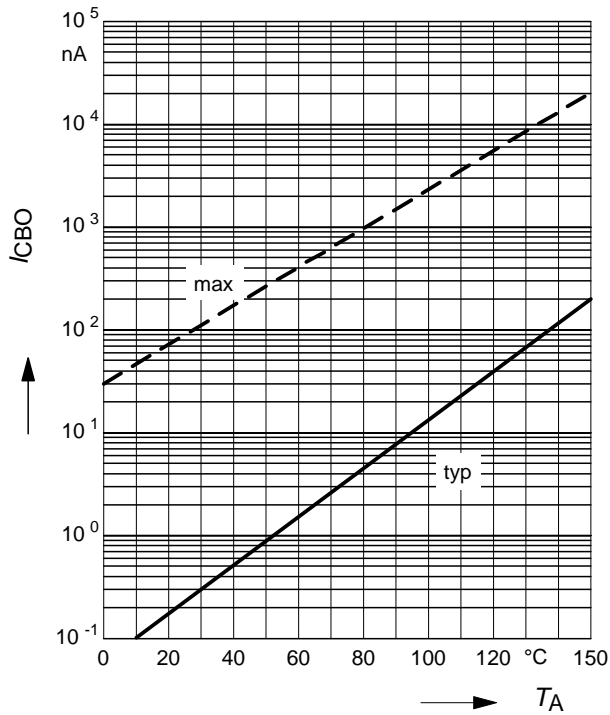
**DC current gain  $h_{\text{FE}} = f(I_C)$**

$$V_{\text{CE}} = 2\text{V}$$



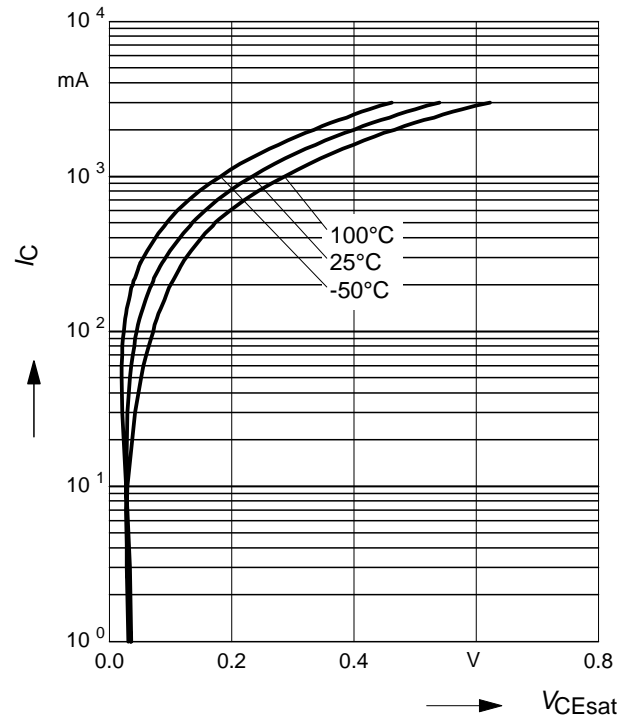
**Collector cutoff current  $I_{CBO} = f(T_A)$**

$V_{CB} = 45V$



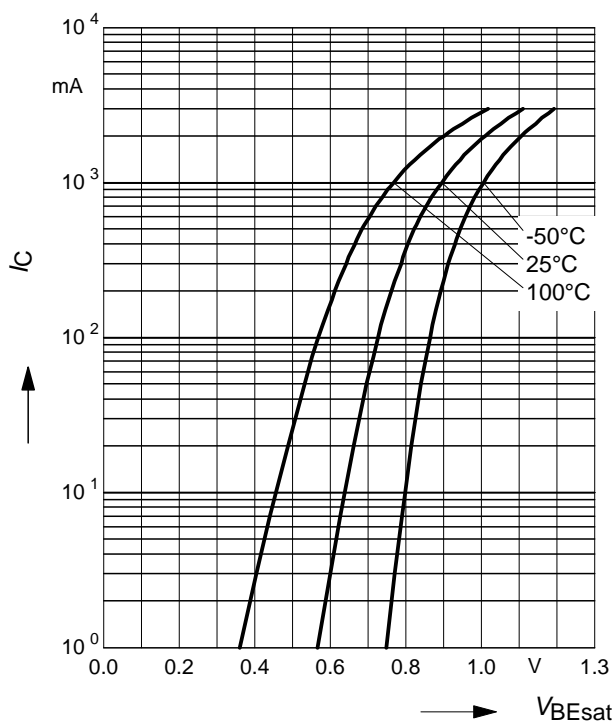
**Collector-emitter saturation voltage**

$I_C = f(V_{CEsat}), h_{FE} = 10$



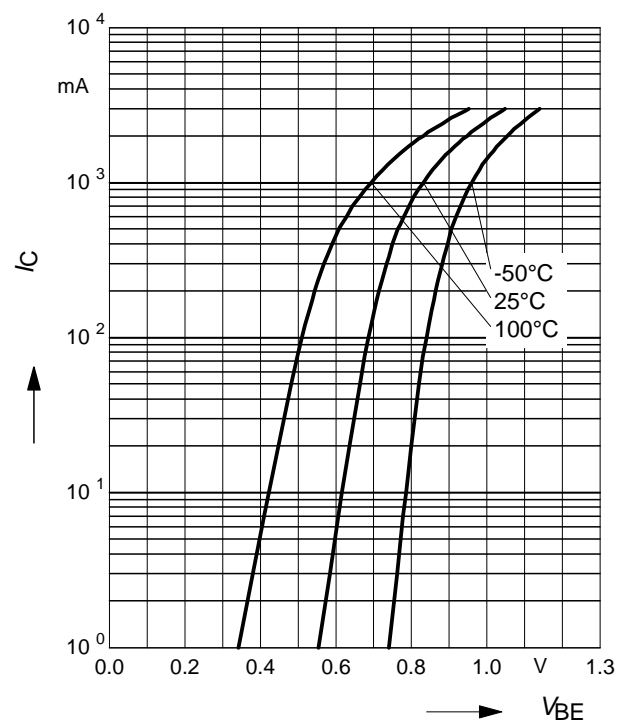
**Base-emitter saturation voltage**

$I_C = f(V_{BEsat}), h_{FE} = 10$



**Collector current  $I_C = f(V_{BE})$**

$V_{CE} = 2V$



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